**LIST OF REFERENCES CITED BY APPLICANT**  
(Use several sheets if necessary)

ATTY DOCKET NO.

7426-083-999

APPLICATION NO

10/705,706

APPLICANT

Fukutomi *et al.*

FILING DATE

November 10, 2003

GROUP

2813  
To be assigned**U.S. PATENT DOCUMENTS**

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>ALL</i>	A33	4,969,257	11/13/90	Sato <i>et al.</i>	—	—	

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
							YES NO

**OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)**


EXAMINER

*Naama Schult*

DATE CONSIDERED

*2/6/05*

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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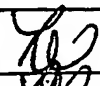
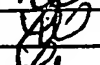



<b>ATTY DOCKET NO.</b> 7426-083-999	<b>APPLICATION NO</b> To be assigned
<b>APPLICANT</b> Fukutomi <i>et al.</i> 10/705706	
<b>FILING DATE</b> November 10, 2003	<b>GROUP</b> 2813 To be assigned

**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>RL</i>	A01	5,579,207	11/01/96	Hayden <i>et al.</i>	_____	_____	
<i>RL</i>	A02	5,467,252	11/01/95	Nomi <i>et al.</i>	_____	_____	
<i>RL</i>	A03	5,399,903	03/21/95	Rostoker <i>et al.</i>	_____	_____	
<i>RL</i>	A04	5,381,039	01/01/95	Morrison	_____	_____	
<i>RL</i>	A05	5,216,278	06/01/93	Lin <i>et al.</i>	_____	_____	
<i>RL</i>	A06	5,173,766	12/22/92	Long <i>et al.</i>	_____	_____	
<i>RL</i>	A07	4,975,765	12/04/90	Ackermann <i>et al.</i>	_____	_____	
<i>RL</i>	A08	4,688,150	08/18/87	Peterson	_____	_____	
<i>RL</i>	A09	4,376,287	03/01/83	Sechi	_____	_____	
<i>RL</i>	A10	3,878,555	04/01/75	Freitag <i>et al.</i>	_____	_____	
<i>RL</i>	A11	3,748,543	07/01/73	Roberson	_____	_____	

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
<i>RL</i>	A12	JP 6053383	02/25/94	JAPAN	_____	_____	X	
<i>RL</i>	A13	JP 5-129473	05/25/93	JAPAN	_____	_____	X	
<i>RL</i>	A14	WO 92/21150	11/26/92	PCT	_____	_____	X	
<i>RL</i>	A15	JP 4277636	10/02/92	JAPAN	_____	_____	X	
<i>RL</i>	A16	JP 4072658	03/06/92	JAPAN	_____	_____	X	
<i>RL</i>	A17	JP 4-26545	03/03/92	JAPAN	_____	_____		
<i>RL</i>	A18	JP 3094459	04/19/91	JAPAN	_____	_____	X	
<i>RL</i>	A19	JP 3094430	04/19/91	JAPAN	_____	_____	X	
<i>RL</i>	A20	WO 90/13991	11/15/90	PCT/US90/01828	_____	_____		
<i>RL</i>	A21	EP 0391790 A1	10/10/90	EUROPE	_____	_____		
<i>RL</i>	A22	JP 2153542	06/13/90	JAPAN	_____	_____	X	
<i>RL</i>	A23	JP 1289273	11/21/89	JAPAN	_____	_____	X	
<i>RL</i>	A24	JP 61222151	10/02/86	JAPAN	_____	_____	X	
<i>RL</i>	A25	JP 60160624	08/22/85	JAPAN	_____	_____	X	
<i>RL</i>	A26	JP 59231825	12/26/84	JAPAN	_____	_____	X	
<i>RL</i>	A27	59-208756	11/27/84	JAPAN	_____	_____	X	
<i>RL</i>	A28	JP 59043554	03/10/84	JAPAN	_____	_____	X	
<i>RL</i>	A29	EP 0 091 072 A	10/12/83	EUROPE	_____	_____		

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)		
	A30	Matsuo <i>et al.</i> , "Smallest Flip-Chip-Like Package 'Chip Scale Package (CSP)"; The Second VLS Packaging Workshop of Japan 1994
	A31	Nikkei Materials & Technology 94.4 (No. 140)
	A32	Tummala <i>et al.</i> ; Microelectronics Packaging Handbook: Semiconductor Packaging Second Edition Part II
EXAMINER		DATE CONSIDERED 
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